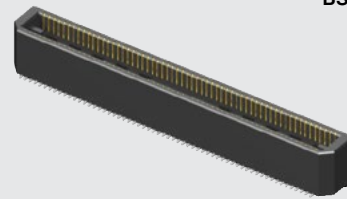


BTE-040-02-L-D-A



BTE-060-02-F-D-A

BSE-020-01-F-D-A



BTE, BSE SERIES

(0.80 mm) .0315"

BASIC BLADE & BEAM HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTE or www.samtec.com?BSE

- Insulator Material:** Liquid Crystal Polymer
- Contact Material:** Phosphor Bronze
- Plating:** Au or Sn over 50 μm (1.27 μm) Ni
- Current Rating:** 2 A per pin (2 pins powered)
- Operating Temp Range:** -55 °C to +125 °C
- Voltage Rating:** 225 VAC with 5 mm Stack Height
- Max Cycles:** 100
- RoHS Compliant:** Yes

PROCESSING

- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0.10 mm) .004" max (020-080) (0.15 mm) .006" max (100-120)* (.004" stencil solution may be available; contact IPG@samtec.com)
- Board Stacking:** For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- 30 μm (0.76 μm) Gold
 - Edge Mount Capability
 - Friction Lock option
 - 11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTE	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION						
Mates with: BSE		Specify LEAD STYLE from chart	<p>-F = Gold Flash on contact, Matte Tin on tail</p> <p>-L = 10 μm (0.25 μm) Gold on contact, Matte Tin on tail</p> <p>-C* = Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails</p> <p>*Note: -C Plating passes 10 year MFG testing</p>			<p>-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad</p> <p>-TR = Tape & Reel (80 positions maximum)</p>						
<p>-020, -040, -060, -080, -100, -120</p>		<table border="1"> <thead> <tr> <th>LEAD STYLE</th> <th>A</th> </tr> </thead> <tbody> <tr> <td>-01</td> <td>(4.27) .168</td> </tr> <tr> <td>-02</td> <td>(7.21) .284</td> </tr> </tbody> </table>	LEAD STYLE	A	-01	(4.27) .168	-02	(7.21) .284				
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<p>MATED HEIGHT</p> <table border="1"> <thead> <tr> <th>LEAD STYLE</th> <th>MATED HEIGHT*</th> </tr> </thead> <tbody> <tr> <td>-01</td> <td>(5.00) .197</td> </tr> <tr> <td>-02</td> <td>(8.00) .315</td> </tr> </tbody> </table> <p>*Processing conditions will affect mated height.</p>		LEAD STYLE	MATED HEIGHT*	-01	(5.00) .197	-02	(8.00) .315					
LEAD STYLE	MATED HEIGHT*											
-01	(5.00) .197											
-02	(8.00) .315											
						<p>POWER/SIGNAL APPLICATION</p> <p>Compatible with UMPT/UMPS for flexible two-piece power/signal solutions</p>						

BSE	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
Mates with: BTE			<p>-F = Gold Flash on contact, Matte Tin on tail</p> <p>-L = 10 μm (0.25 μm) Gold on contact, Matte Tin on tail</p> <p>-C* = Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails</p> <p>*Note: -C Plating passes 10 year MFG testing</p>			<p>-TR = Tape & Reel (80 positions maximum)</p>
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Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.